Power MOSFETS

DATASHEET

LM30025NAK8A

N-Channel

Enhancement Mode MOSFET

Leadpower-semi CO., LTD.

sales@leadpower-semi.com

(03) 6577339　FAX：(03) 6577229

www.leadpower-semi.com

Quality Management Systems

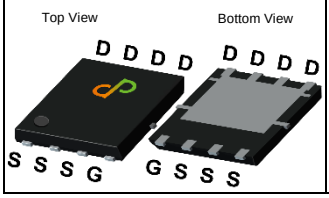
ISO 9001:2015 Certificate

LM30025NAK8A

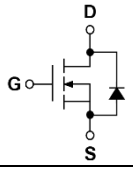
N-Channel Enhancement Mode MOSFET

Pin Description

PDFN5*6



Symbol



Product Summary

Symbol	N-Channel	Unit
V_{DSS}	30	V
$R_{DS(ON)-Max}$	2.5	mΩ
ID	115	A

Feature

- Low Rdson and low conduction loss
- Surface mount package
- Reliable and Rugged
- ROHS Compliant & Halogen-Free

Applications

- DC/DC Converters
- Motor Control

Ordering Information

Orderable Part Number	Package Type	Form	Shipping	Marking
LM30025NAK8A	PDFN5*6	Tape & Reel	5000 / Tape & Reel	30025 □□□□□□

Note：□□□□□□ = Lot Code

Absolute Maximum Ratings (T_J=25°C Unless Otherwise Noted)

Symbol	Parameter		N-Channel	Unit
V_{DSS}	Drain-Source Voltage		30	V
V_{GSS}	Gate-Source Voltage		±20	
T_J	Maximum Junction Temperature		150	°C
T_{STG}	Storage Temperature Range		-55 to 150	°C
I_S	Diode Continuous Forward Current	T_C=25°C	46	A
I_{DM}①	Pulse Drain Current Tested	T_C=25°C	141	A
I_D	Continuous Drain Current	T_C=25°C	115	A
		T_C=100°C	73	
P_D	Maximum Power Dissipation	T_C=25°C	50	W
		T_C=100°C	20	
I_D	Continuous Drain Current	T_A=25°C	25.8	A
		T_A=70°C	20.7	
P_D	Maximum Power Dissipation	T_A=25°C	2.5	W
		T_A=70°C	1.6	
I_{AS}②	Avalanche Current, Single pulse	L=0.1mH	45	A
		L=0.5mH	24	
E_{AS}②	Avalanche Energy, Single pulse	L=0.1mH	101	mJ
		L=0.5mH	144	

Thermal Characteristics

Symbol	Parameter		Rating	Unit
$R_{\theta JC}$	Thermal Resistance-Junction to Case	Steady State	2.5	°C/W
$R_{\theta JA}$③	Thermal Resistance-Junction to Ambient	Steady State	50	°C/W

Note ①：Max. current is limited by bonding wire

Note ②：UIS tested and pulse width are limited by maximum junction temperature 150°C

Note ③：Surface Mounted on 1in^2 FR-4 board with 1oz

N-Channel Electrical Characteristics (T_J=25°C Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V, I_{DS}=250uA	30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=24V, V_{GS}=0V	-	-	1	uA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_{DS}=250uA	1	1.5	2	V
I_{GSS}	Gate Leakage Current	V_{GS}=±20V, V_{DS}=0V	-	-	±100	nA
$R_{DS(ON)}$④	Drain-Source On-state Resistance	V_{GS}=10V, I_{DS}=20A	-	2.1	2.5	mΩ
		V_{GS}=4.5V, I_{DS}=15A		2.8	3.6	
gfs	Forward Transconductance	V_{DS}=5V, I_{DS}=20A	-	38	-	S
Dynamic Characteristics ⑤						
R_G	Gate Resistance	V_{GS}=0V,V_{DS}=0V, Freq.=1MHz	-	2.6	-	Ω
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=15V, Freq.=1MHz	-	4242	-	pF
C_{oss}	Output Capacitance		-	492	-	
C_{rss}	Reverse Transfer Capacitance		-	329	-	
$td_{(ON)}$	Turn-on Delay Time	V_{GS}=10V,V_{DS}=15V, I_D=1A,R_{GEN}=2.5Ω	-	33	-	nS
t_r	Turn-on Rise Time		-	23	-	
$t_{d(OFF)}$	Turn-off Delay Time		-	72	-	
t_f	Turn-off Fall Time		-	25	-	
Q_g	Total Gate Charge	V_{GS}=4.5V,V_{DS}=25V I_D=14A	-	46	-	nC
Q_g	Total Gate Charge	V_{GS}=10V,V_{DS}=25V, I_D=14A	-	88	-	
Q_{gs}	Gate-Source Charge		-	7.3	-	
Q_{gd}	Gate-Drain Charge		-	24	-	
Source-Drain Characteristics						
V_{SD}④	Diode Forward Voltage	I_{SD}=15A, V_{GS}=0V	-	0.8	1.1	V
t_{rr}	Reverse Recovery Time	I_F=15A, V_R=0V dI$_F$/dt=100A/μs	-	19.8	-	nS
Q_{rr}	Reverse Recovery Charge		-	8.7	-	nC

Note ④：Pulse test (pulse width≤300us, duty cycle≤2%).
Note ⑤：Guaranteed by design, not subject to production testing.

N-Channel Typical Characteristics

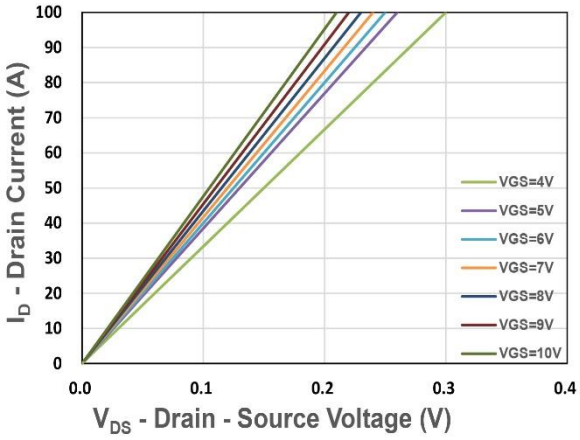


Figure 1. Output Characteristics

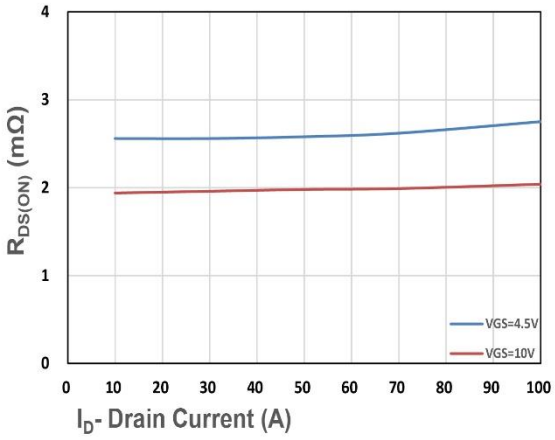


Figure 2. On-Resistance vs. ID

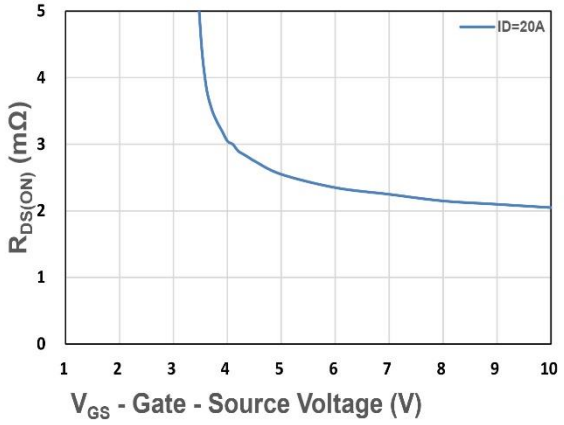


Figure 3. On-Resistance vs. VGS

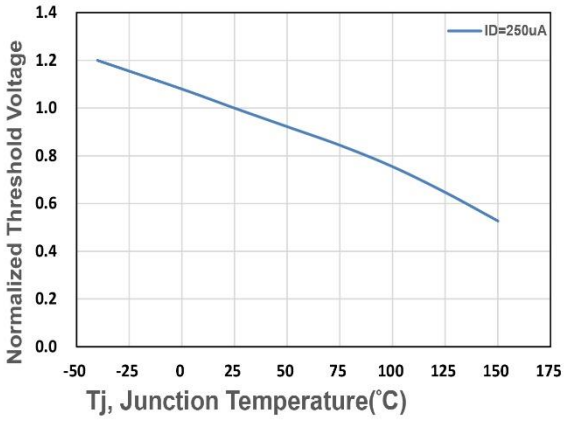


Figure 4. Gate Threshold Voltage

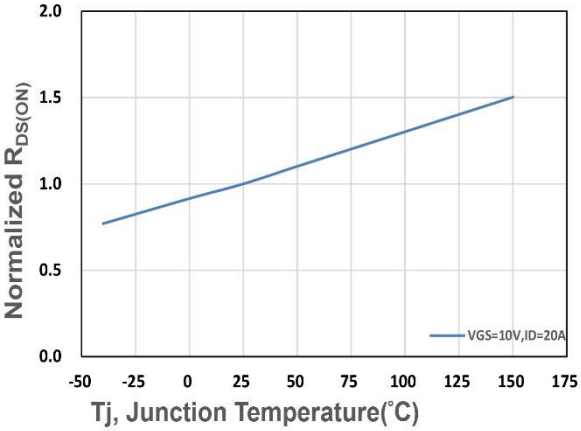


Figure 5. Drain-Source On Resistance

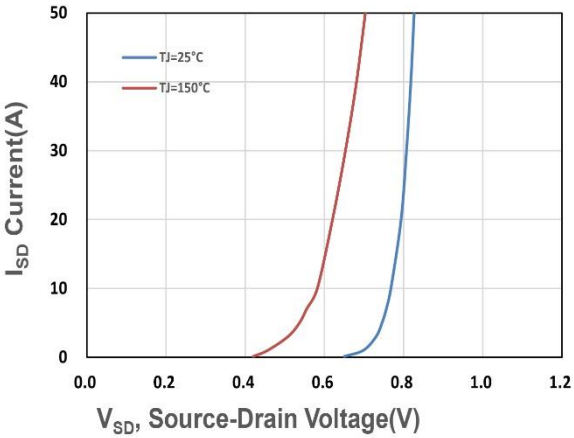


Figure 6. Source-Drain Diode Forward

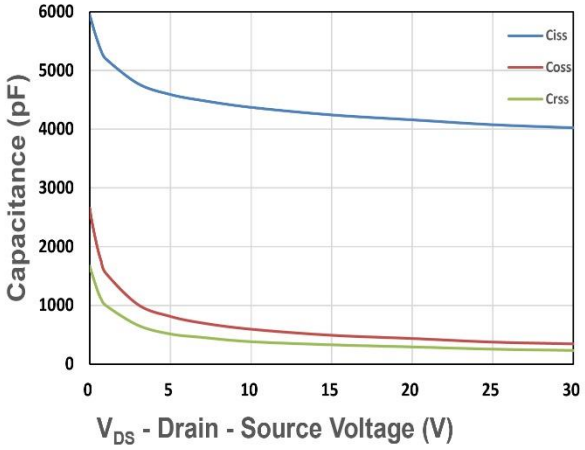


Figure 7. Capacitance

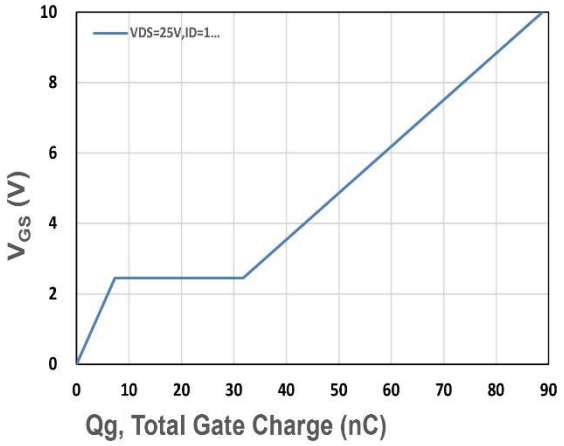


Figure 8. Gate Charge Characteristics

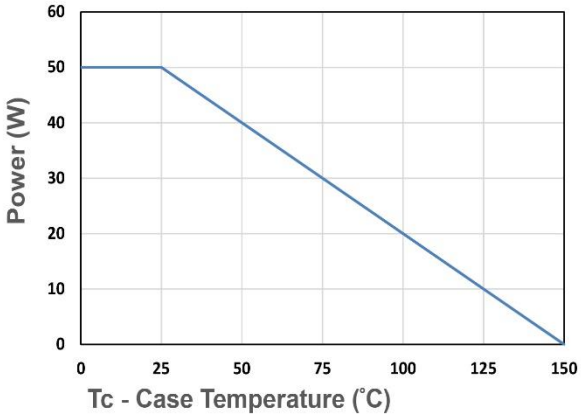


Figure 9. Power Dissipation

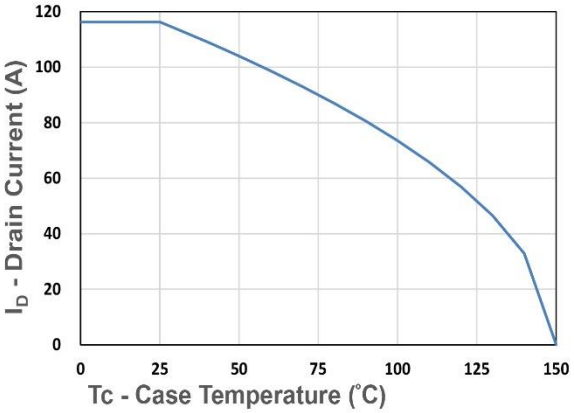


Figure 10. Drain Current

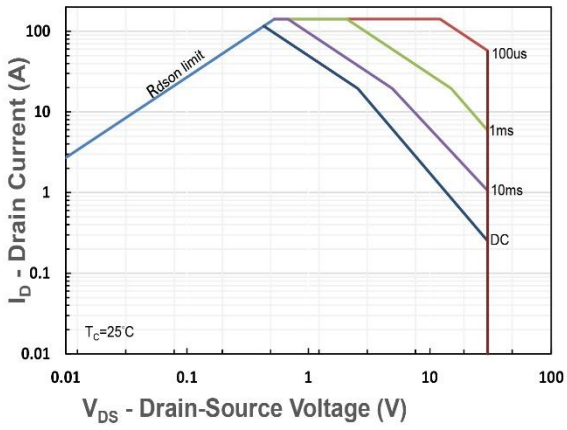


Figure 11. Safe Operating Area

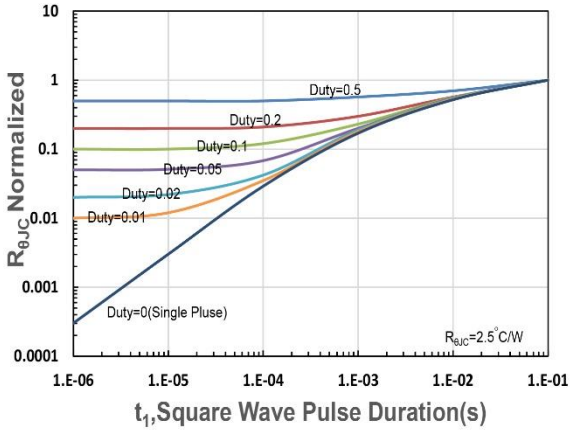


Figure 12. RθJC Transient Thermal Impedance